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(54) **ELECTRONIC DEVICE INCLUDING SHIELDING MEMBER INCLUDING STRUCTURE FOR REDUCING DEFORMATION**

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(57) **ABSTRACT**

An electronic device according to an embodiment includes a printed circuit board including a ground pad, an optical sensor disposed on the printed circuit board, and a shielding member covering the optical sensor. The shielding member includes a first adhesive layer attached on the optical sensor and the ground pad, a first shielding layer electrically connected to the ground pad and disposed on the first adhesive layer, and a first cover layer disposed on the first shielding layer, the first cover layer including a plurality of first particles configured to reflect or scatter light, a plurality of second particles configured to absorb the light, and a binder covering the plurality of first particles and the plurality of second particles.

